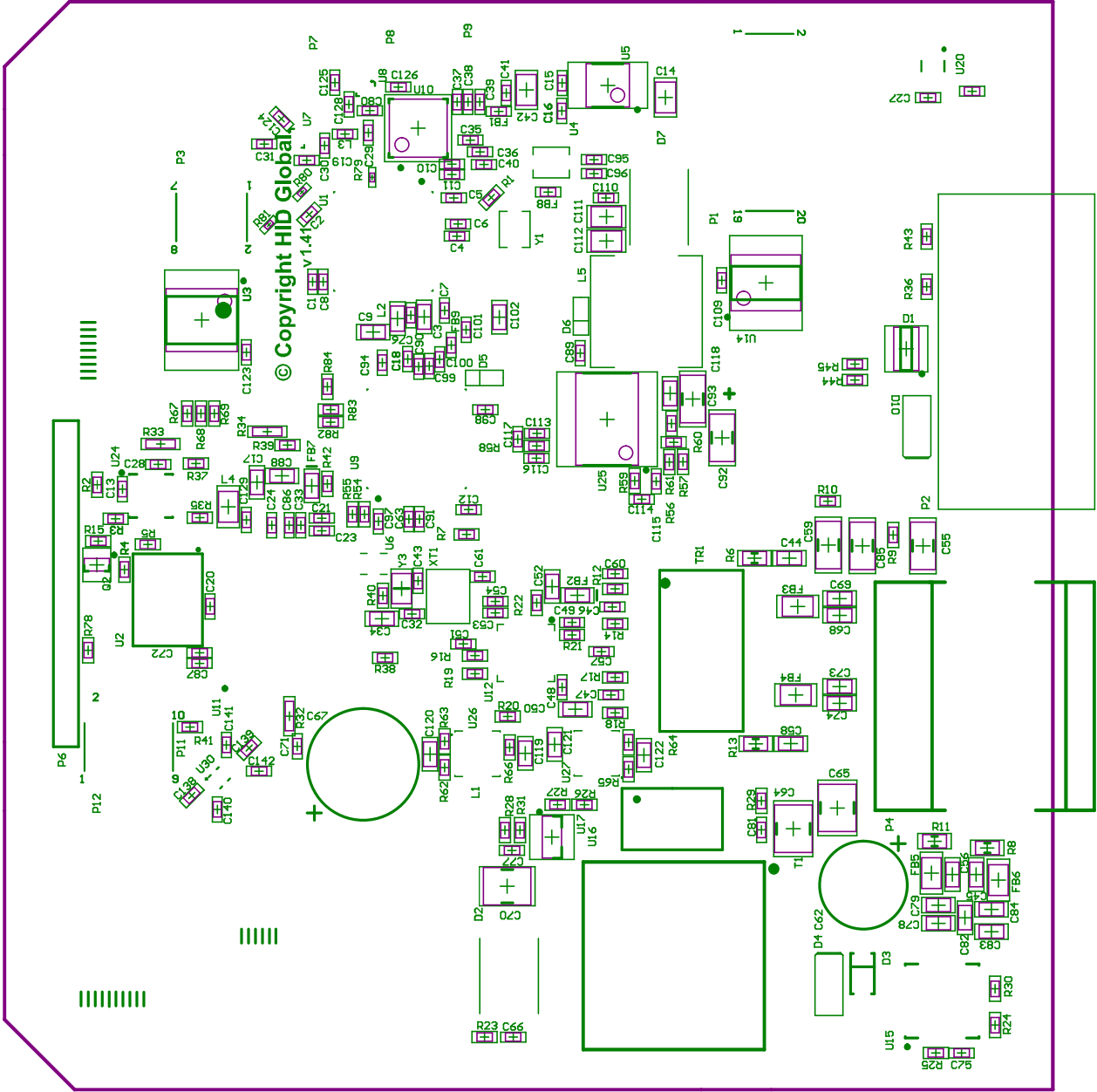


Board File Name: Design Name.		blufi_poe.PcbDoc btWifi_poe	
Hole Count:		894	
Via Count:		841	
Pad Count:		1034	
Board Material:		FR408	
Number of Layers:		4	
Copper Weight:		1 Oz	
Finished Board Thickness:		0.8 mm	
Min Trace:		5mil	
Min Space:		4mil	
Soldermask type:		LPI BLUE	
Pad finish:		ENIG	
Silkscreen Color:		WHITE	
Minimum Via Size:		Drill	Dia
		10mil	20mil
Files:		GTL Top Layer: Top Soldermask: GTS Top Paste: GTP Top Silkscreen: GTO Signal 1 G1 Signal 2 G2 Bottom Layer: GBL Bottom Soldermask: GBS Bottom Paste: GBP Bottom Silkscreen: GBO	
Board Outline:		GM1cut according to this layer	
Drill:		TXT Top-Bottom	
Documentation:		PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1		5.10mil	3.65	
2	Signal Layer 1	FR408	1.40mil		
	Dielectric 3	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

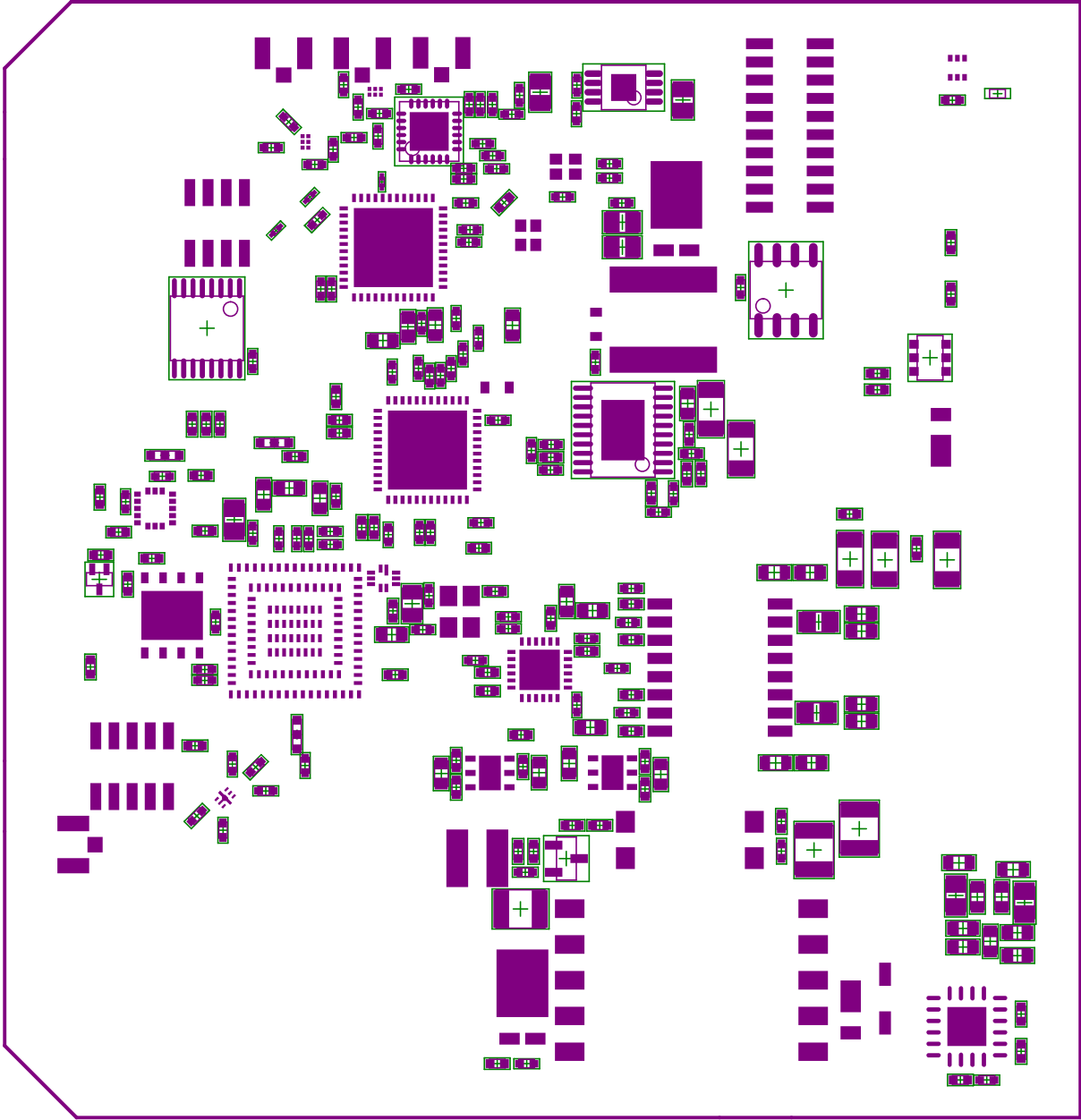


Board File Name: blufi_poe.PcbDoc	
Design Name: btWifi_poe	
Hole Count:	894
Via Count:	841
Pad Count:	1034
Board Material: FR408	
Number of Layers: 4	
Copper Weight: 1 Oz	
Finished Board Thickness: 0.8 mm	
Min Trace: 5mil	
Min Space: 4mil	
Soldermask type: LPI BLUE	
Pad finish: ENIG	
Silkscreen Color: WHITE	
Drill	Dia
10mil	20mil
Files:	
Top Layer: GTL	
Top Soldermask: GTS	
Top Paste: GTP	
Top Silkscreen: GTO	
Signal 1: G1	
Signal 2: G2	
Bottom Layer: GBL	
Bottom Soldermask: GBS	
Bottom Paste: GBP	
Bottom Silkscreen: GBO	
Board Outline: GM1 cut according to this layer	
Drill: TXT Top-Bottom	
Documentation: PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1				
2	Signal Layer 1	FR408	5.10mil	3.65	
	Dielectric 2				
3	Signal Layer 2	FR408	18.00mil	4.03	
	Dielectric 3				
4	Bottom Layer	FR408	1.40mil	3.65	
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

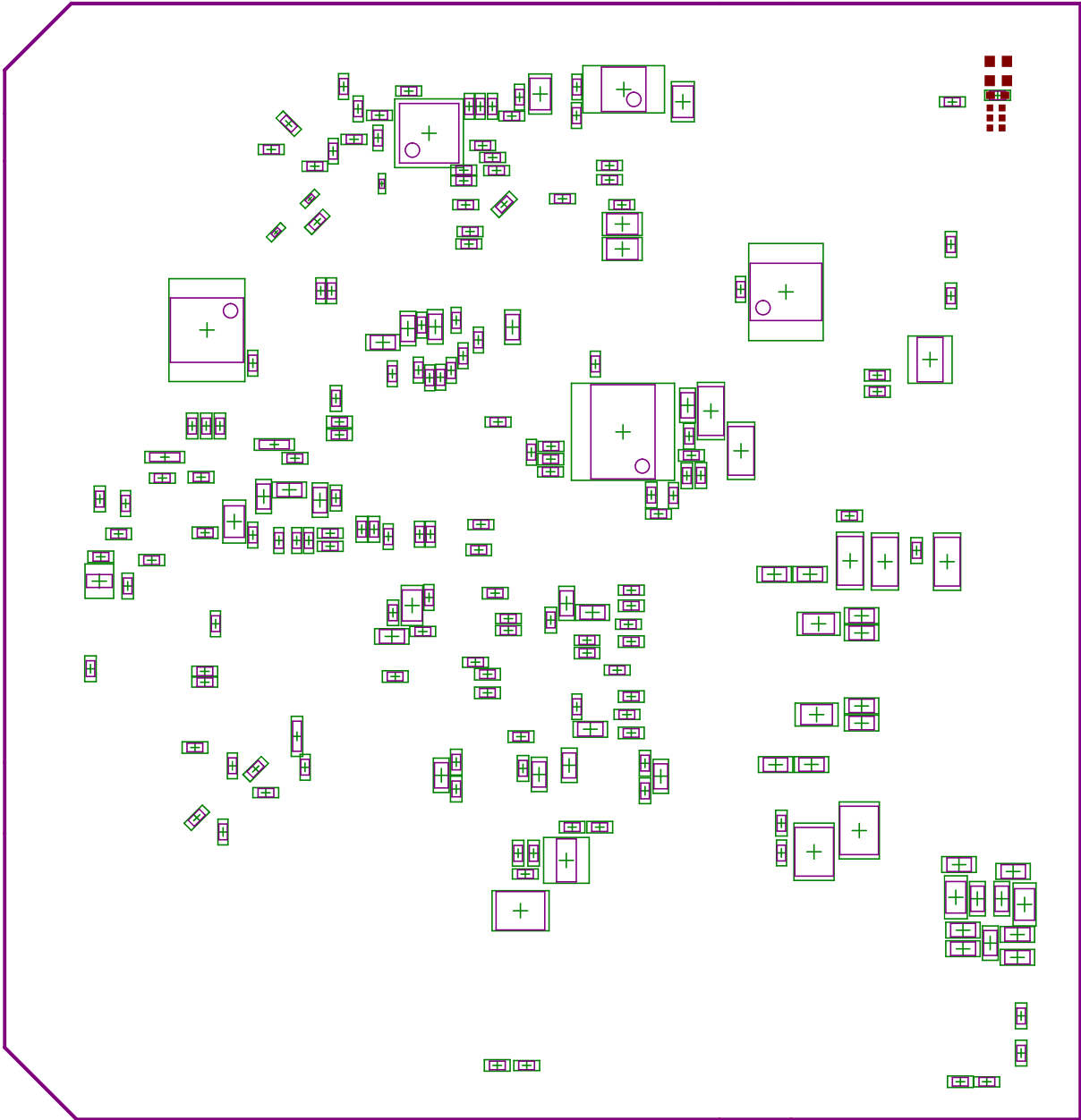


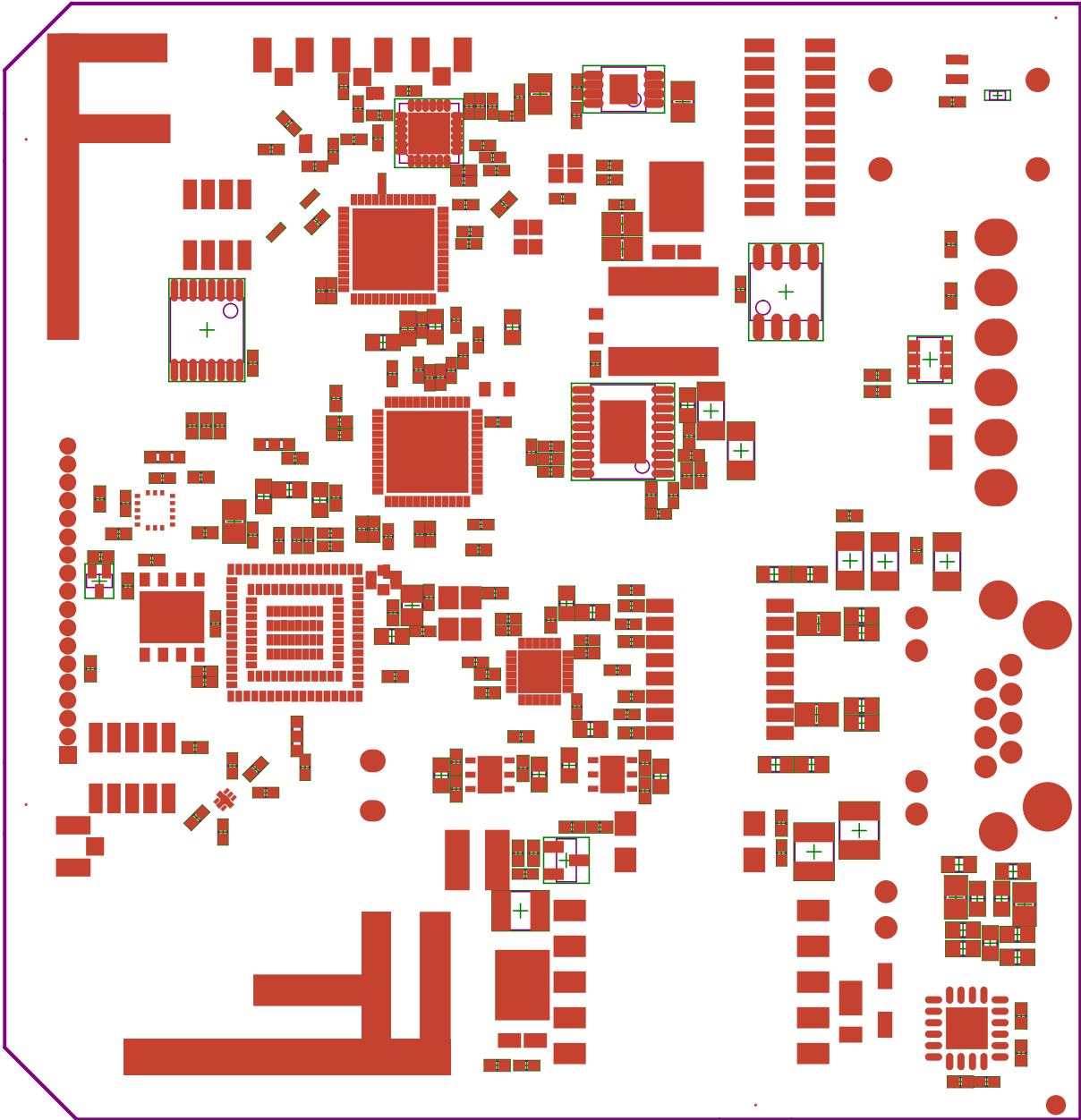
Board File Name: Design Name:		blufi_poe.PcbDoc btWifi_poe			
Hole Count:		894			
Via Count:		841			
Pad Count:		1034			
Board Material:		FR408			
Number of Layers:		4			
Copper Weight:		1 Oz			
Finished Board Thickness:		0.8 mm			
Min Trace:		5mil			
Min Space:		4mil			
Soldermask type:		LPI BLUE			
Pad finish:		ENIG			
Silkscreen Color:		WHITE			
Minimum Via Size:		Drill	Dia		
		10mil	20mil		
Files:					
Top Layer:		GTL			
Top Soldermask:		GTS			
Top Paste:		GTP			
Top Silkscreen:		GTO			
Signal 1		G1			
Signal 2		G2			
Bottom Layer:		GBL			
Bottom Soldermask:		GBS			
Bottom Paste:		GBP			
Bottom Silkscreen:		GBO			
Board Outline:		GM1cut according to this layer			
Drill:		TXT	Top-Bottom		
Documentation:		PDF			
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric 3				
	Signal Layer 2	FR408	18.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2				
	Bottom Layer	FR408	5.10mil	3.65	
4	Bottom Solder		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



Board File Name: blufi_poe.PcbDoc	
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Hole Count:	894
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Board Material: FR408	
Number of Layers: 4	
Copper Weight: 1 Oz	
Finished Board Thickness: 0.8 mm	
Min Trace: 5mil	
Min Space: 4mil	
Soldermask type: LPI BLUE	
Pad finish: ENIG	
Silkscreen Color: WHITE	
Drill	Dia
10mil	20mil
Files:	
Top Layer: GTL	
Top Soldermask: GTS	
Top Paste: GTP	
Top Silkscreen: GTO	
Signal 1: G1	
Signal 2: G2	
Bottom Layer: GBL	
Bottom Soldermask: GBS	
Bottom Paste: GBP	
Bottom Silkscreen: GBO	
Board Outline: GM1 cut according to this layer	
Drill:	TXT Top-Bottom
Documentation: PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Signal Layer 1	FR408	5.10mil	3.65	
2			1.40mil		
	Dielectric 3				
	Signal Layer 2	FR408	18.00mil	4.03	
3			1.40mil		
	Dielectric 2				
	Bottom Layer	FR408	5.10mil	3.65	
4			1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



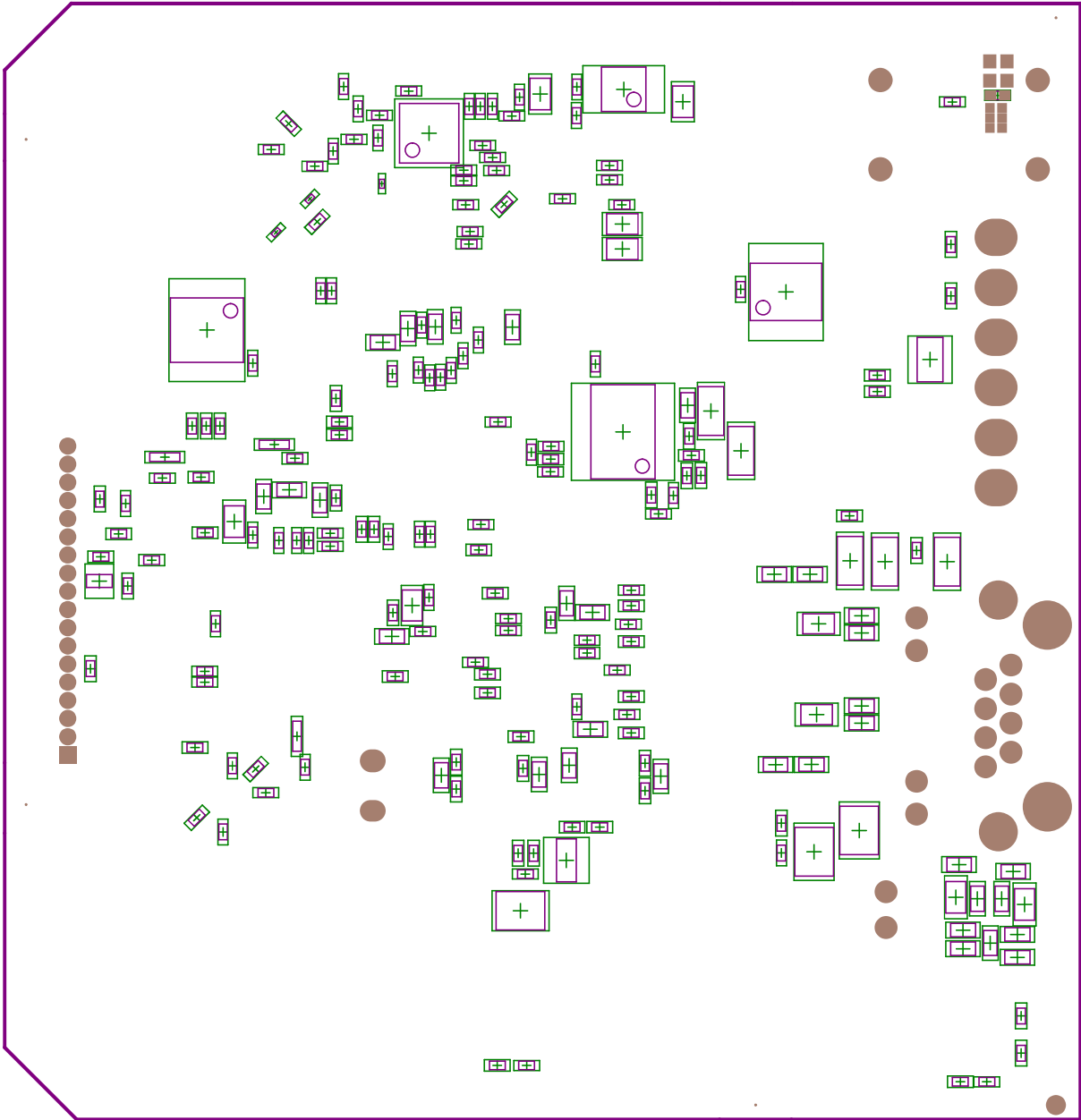


Board File Name:	blufi_poe.PcbDoc
Design Name:	btWifi_poe
Hole Count:	894
Via Count:	841
Pad Count:	1034
Board Material:	FR408
Number of Layers:	4
Copper Weight:	1 Oz
Finished Board Thickness:	0.8 mm
Min Trace:	5mil
Min Space:	4mil
Soldermask type:	LPI BLUE
Pad finish:	ENIG
Silkscreen Color:	WHITE
Minimum Via Size:	Drill 10mil Dia 20mil
Files:	GTL Top Layer: Top Soldermask: Top Paste: Top Silkscreen: Signal 1 Signal 2 Bottom Layer: Bottom Soldermask: Bottom Paste: Bottom Silkscreen: GTS GTP GTO G1 G2 GBL GBS GBP GBO
Board Outline:	GM1cut according to this layer
Drill:	TXT Top-Bottom
Documentation:	PDF

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
2	Signal Layer 1	FR408	5.10mil	3.65	
	Dielectric 3	FR408	18.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

Board File Name: blufi_poe.PcbDoc	
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Copper Weight: 1 Oz	
Finished Board Thickness: 0.8 mm	
Min Trace: 5mil	
Min Space: 4mil	
Soldermask type: LPI BLUE	
Pad finish: ENIG	
Silkscreen Color: WHITE	
Minimum Via Size:	Drill 10mil Dia 20mil
Files:	
Top Layer: GTL	
Top Soldermask: GTS	
Top Paste: GTP	
Top Silkscreen: GTO	
Signal 1: G1	
Signal 2: G2	
Bottom Layer: GBL	
Bottom Soldermask: GBS	
Bottom Paste: GBP	
Bottom Silkscreen: GBO	
Board Outline: GM1 cut according to this layer	
Drill: TXT Top-Bottom	
Documentation: PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric 3	FR408	16.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



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10mil	20mil
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Signal 2: G2	
Bottom Layer: GBL	
Bottom Soldermask: GBS	
Bottom Paste: GBP	
Bottom Silkscreen: GBO	
Board Outline: GM1cut according to this layer	
Drill: TXT Top-Bottom	
Documentation: PDF	

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric1				
	Top Layer	FR408	5.10mil	3.65	
2	Signal Layer 1		1.40mil		
	Dielectric1				
	Signal Layer 1	FR408	18.00mil	4.03	
3	Signal Layer 2		1.40mil		
	Dielectric 2				
	Signal Layer 2	FR408	5.10mil	3.65	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

